



THE UNITED STATES PATENT AND TRADEMARK OFFICE

7/B 7/20/02
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In re Application of:

William E. Bernier et al.

Serial No.: 09/687,524

Art Unit: 1725

Filed: October 12, 2000

Examiner: Johnson, J.

For: SOLDER PROTECTIVE
COATING AND
FLUXLESS JOINING OF
FLIP CHIP DEVICES ON
LAMINATES WITH
PLATED SOLDER.

Atty Docket: END920000034US1
(20135/0311)

RESPONSE AND AMENDMENT UNDER 37 CFR § 1.111

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated April 19, 2002, please amend the
above-identified application as follows:

IN THE CLAIMS:

Kindly amend claim 1 as follows:

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TC 1700

- Sub C1
B1
1. (Amended) A method of protecting tin solderable surfaces comprising:
providing a solderable surface having tin oxide thereon;
applying complexing agent to said solderable surface;
forming a protected solderable surface by forming a reaction product
with said tin oxide and said complexing agent, wherein said reaction product

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